

High-productivity, high-precision THT bonding system

MYSmart[™] series MYC50E inline THT bonding system



MYC50E THT bonding platform

Protect your electronics

The MYSmart MYC50E is an industrial dispensing system expertly developed for THT bonding applications.

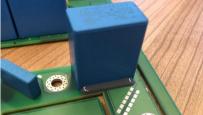
- 1. Fast and stable operation
- 2. Flexible multi-axis control for complex processes
- 3. Seamless integration of an external feeding system
- 4. Extended hood for neat hose routing with counterbalances
- 5. Coupling of a robust and versatile high-pressure valve
- 6. Micrometer precision fine adjustment
- 7. Needle correction module eliminates the effect of needle change on position degree
- 8. Precision electronic scale module to monitor and maintain process repeatability.



Bonding of THT components

THT components are typically tall components connected to a PCB by wires going through the board and soldered on the opposite side. These components are sensitive for mechanical stress. In order to better protect these components, one or two component materials can be dispensed between THT components, or in the collar of these components and the PCB board.









V-300HP High Pressure Valve



Characteristics

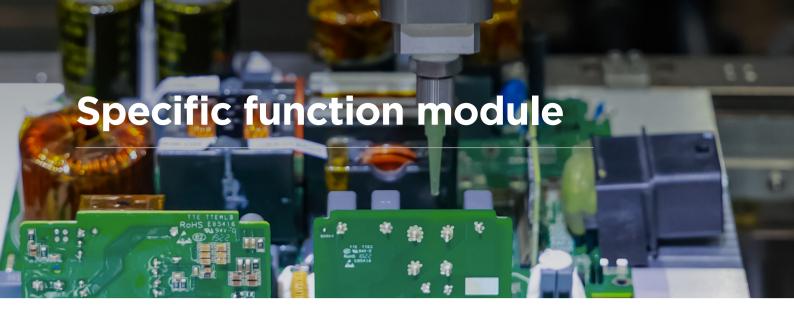
- · Adjustable suckback, clean fluid break
- · Adjustable amount of fluid at the beginning and the end
- · Full stainless steel structure, robust and durable
- \cdot Dual air path design, quick opening and closing
- · Easy disassembly and maintenance

1K Progressive Cavity Pump



Characteristics

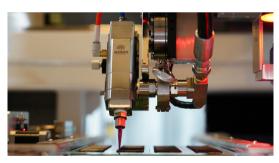
- · Volumetric dispensing for the highest repeatability
- \cdot Volumetric reverse for a clean dispense and no drooling
- · Flow rate is easily adjusted to meet process requirements
- · Precision dosing control for uniform geometry of a continuous bead or area fill
- · Sealed system does not drip, even with water under pressure



In order to efficiently implement complex process applications, the MYC50E is designed with a variety of process function module.



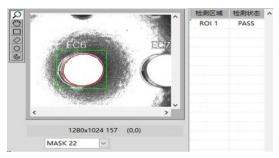
Nozzle cleaning cup



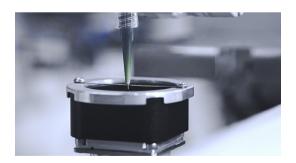
Tilt & rotate module



Needle calibration



THT Inspection



Electronic weight scale



Micrometer calibration

Specifications **MYC50E**

MOTION SYSTEM		
Z-axis repeatability	±25um@3σ	
X-Y repeatability	±25um@3 σ	
Z-axis positioning accuracy	±30um@3σ	
XY-axis positioning accuracy	±50um@3σ	
X-Y acceleration	0.8g	
X-Y velocity	800mm/s	
Z travel	100mm	
Drive system	AC servo motor with precise ball screw	
DISPENSING AREA(XxY)		
v-300HP single valve and single lane(XxY)	600x430/490x320(with tilt &rotate)	
V-9000H single valve and single lane(XxY)	600x420/400x280(with tilt &rotate)	
BOARD HANDLING		
Max. board/carrier length	650mm (1 station)/ 450 mm (2 stations)	
Min. board/carrier length	50mm	
Max. board/carrier width	500mm	
Min. board/carrier width	50mm	
Min board edge	3mm	
Max. top clearance	100mm	
Max. bottom clearance	100mm	
Number of station	One station/Dual station(optional)	
Number of conveyor	Single lane/Dual lane(optional)	
Load capacity	5kg, 10kg(optional)	
Operation modes	SMEMA	
Standard conveyor type	Pin chain type	
FACILITIES REQUIREMENTS		
System footprint MYC50E (WxDxH)	1,290x1,364x2,120mm (without light tower)	
Air supply	80 psi (5.5 bar)	
Power	AC220V, 2.5kW, 16A,50/60 Hz	
System weight	1,020Kg	
Standards compliance	SMEMA; CE ; RoH	IS .
CONTROL SYSTEM		
Туре	IPC with monitor and keyboard	
Operating system	Win 10 / Win 11	
Software	MYSmart dispens	er software
VISION AND LIGHTING		
Camera resolution	1.3M pixels	
STANDARD FEATURES		
Nozzle cleaning cup		Audible light alarm device
Conveyor edge clamping system		Low air pressure sensor for general air supply
ndustrial computer and software and monitor		
OPTIONAL FEATURES		
_aser height sensor		Barcode reader
Electronic weight scale		Hand held barcode reader
Micrometer calibration module		THT inspection software(color camera)
Clamping wipe cleaning module		Titt inspection software (color carriera)

Bringing tomorrow's electronics to life







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